

Dual N-Channel 30 V (D-S) MOSFETs

PRODUCT SUMMARY

	V _{DS} (V)	R _{DS(on)} (Ω) (Max.)	I _D (A)	Q _g (Typ.)
Channel-1	30	0.0058 at V _{GS} = 10 V	40 ^a	12.5 nC
		0.0075 at V _{GS} = 4.5 V	40 ^a	
Channel-2	30	0.0030 at V _{GS} = 10 V	40 ^a	29 nC
		0.0035 at V _{GS} = 4.5 V	40 ^a	

FEATURES

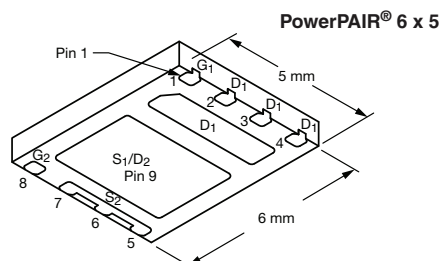
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFETs
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

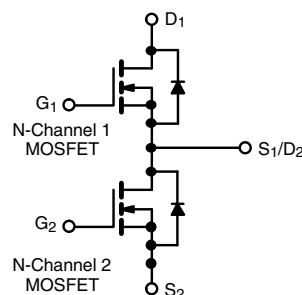
- Notebook System Power
- POL
- Synchronous Buck Converter



RoHS
COMPLIANT
HALOGEN
FREE



Ordering Information: SiZ910DT-T1-GE3 (Lead (Pb)-free and Halogen-free)



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

Parameter		Symbol	Channel-1	Channel-2	Unit
Drain-Source Voltage		V _{DS}	30		V
Gate-Source Voltage		V _{GS}	± 20		
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	I _D	40 ^a	40 ^a	A
	T _C = 70 °C		40 ^a	40 ^a	
	T _A = 25 °C		22 ^{b, c}	32 ^{b, c}	
	T _A = 70 °C		17 ^{b, c}	26 ^{b, c}	
Pulsed Drain Current (t = 300 μs)		I _{DM}	100	120	
Continuous Source Drain Diode Current	T _C = 25 °C	I _S	24 ^a	28 ^a	
	T _A = 25 °C		3.8 ^{b, c}	4.3 ^{b, c}	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	25	40	mJ
Single Pulse Avalanche Energy		E _{AS}	31	80	
Maximum Power Dissipation	T _C = 25 °C	P _D	48	100	W
	T _C = 70 °C		31	64	
	T _A = 25 °C		4.6 ^{b, c}	5.2 ^{b, c}	
	T _A = 70 °C		3 ^{b, c}	3.3 ^{b, c}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C
Soldering Recommendations (Peak Temperature) ^{d, e}			260		

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Channel-1		Channel-2		Unit
		Typ.	Max.	Typ.	Max.	
Maximum Junction-to-Ambient ^{b, f}	R _{thJA}	22	27	19	24	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	2.1	2.6	1	1.25	

Notes:

a. Package limited - T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. See solder profile (www.vishay.com/doc?73257). The PowerPAIR is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under steady state conditions is 62 °C/W for channel-1 and 55 °C/W for channel-2.

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions		Min.	Typ.	Max.	Unit
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	Ch-1	30			V
		V _{GS} = 0 V, I _D = 250 μA	Ch-2	30			
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA	Ch-1		33		mV/°C
		I _D = 250 μA	Ch-2		31		
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA	Ch-1		- 5.4		
		I _D = 250 μA	Ch-2		- 6.1		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	Ch-1	1.2		2.2	V
		V _{DS} = V _{GS} , I _D = 250 μA	Ch-2	1		2.2	
Gate Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	Ch-1			± 100	nA
			Ch-2			± 100	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	Ch-1			1	μA
		V _{DS} = 30 V, V _{GS} = 0 V	Ch-2			1	
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	Ch-1			5	
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	Ch-2			5	
On-State Drain Current ^b	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-1	20			A
		V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-2	25			
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A	Ch-1		0.0048	0.0058	Ω
		V _{GS} = 10 V, I _D = 20 A	Ch-2		0.0025	0.0030	
		V _{GS} = 4.5 V, I _D = 20 A	Ch-1		0.0060	0.0075	
		V _{GS} = 4.5 V, I _D = 20 A	Ch-2		0.0029	0.0035	
Forward Transconductance ^b	g _{fs}	V _{DS} = 10 V, I _D = 20 A	Ch-1		94		S
		V _{DS} = 10 V, I _D = 20 A	Ch-2		140		
Dynamic ^a							
Input Capacitance	C _{iss}	Channel-1 V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	Ch-1		1500		pF
			Ch-2		3600		
Output Capacitance	C _{oss}	Channel-2 V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	Ch-1		285		
			Ch-2		660		
Reverse Transfer Capacitance	C _{rss}	Channel-1 V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	Ch-1		125		nC
			Ch-2		305		
Total Gate Charge	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 20 A	Ch-1		26	40	
		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 20 A	Ch-2		60	110	
Gate-Source Charge	Q _{gs}	Channel-1 V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 20 A	Ch-1		12.5	19	
			Ch-2		29	51	
Gate-Drain Charge	Q _{gd}	Channel-2 V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 20 A	Ch-1		4.7		
			Ch-2		10		
Gate Resistance	R _g	f = 1 MHz	Ch-1	0.5	2.6	5.2	Ω
			Ch-2	0.1	0.6	1.2	

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.



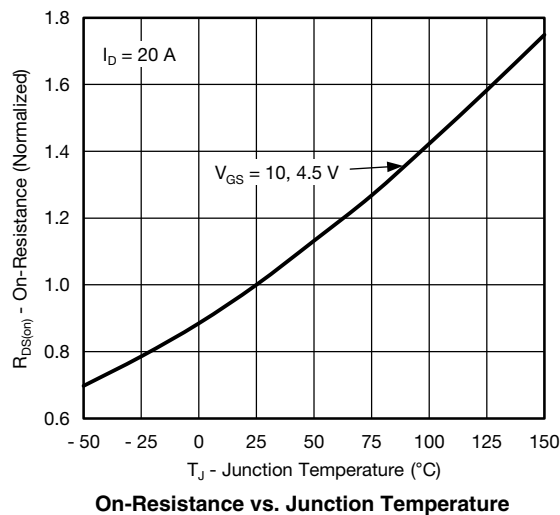
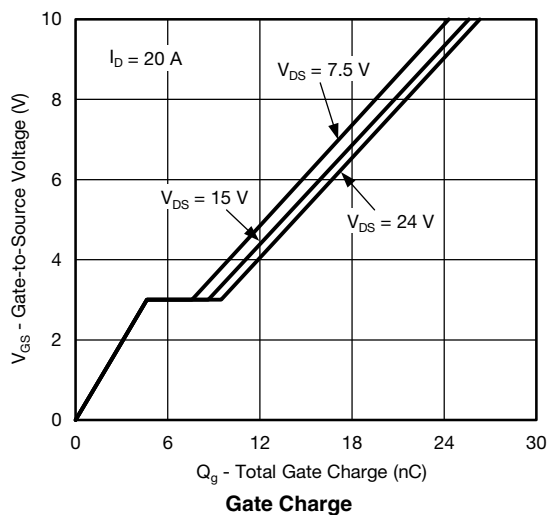
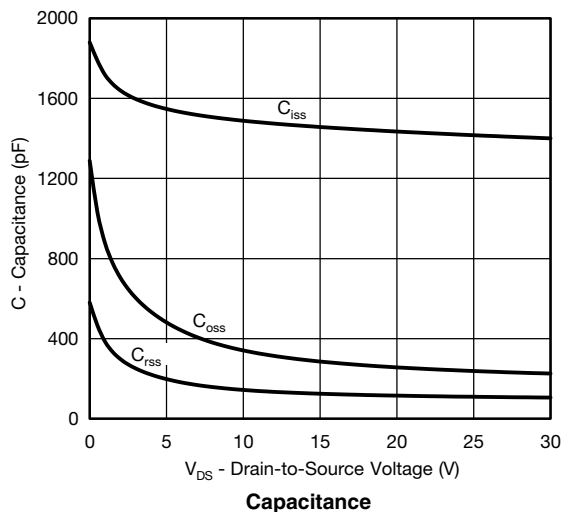
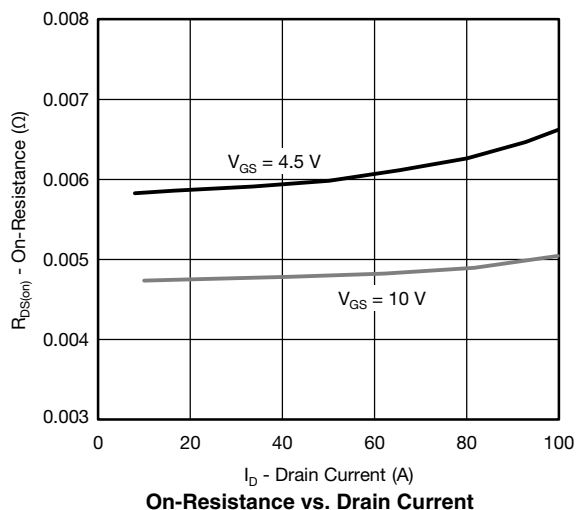
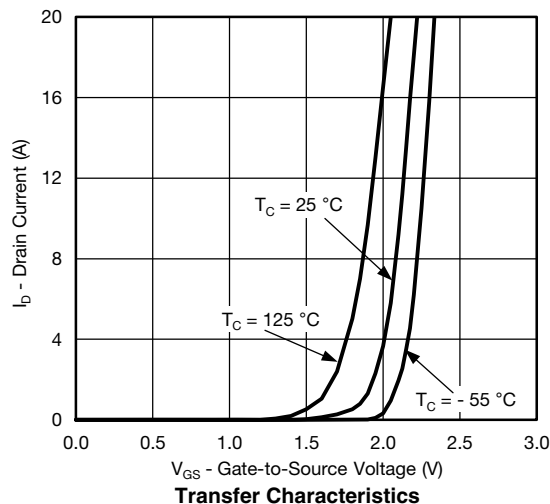
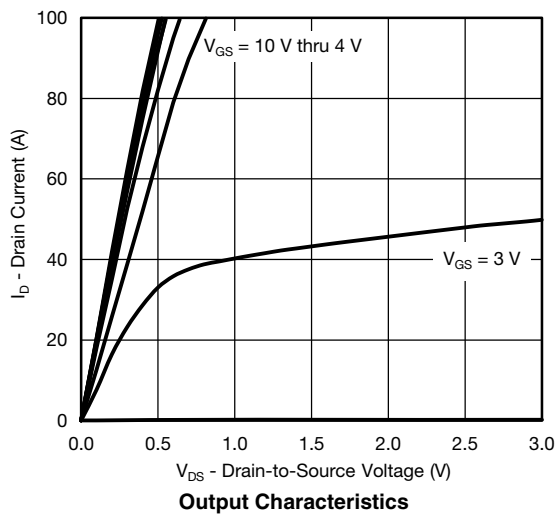
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Dynamic ^a							
Turn-On Delay Time	t _{d(on)}	Channel-1 V _{DD} = 15 V, R _L = 1.5 Ω I _D ≅ 10 A, V _{GEN} = 4.5 V, R _g = 1 Ω	Ch-1		20	40	ns
			Ch-2		30	60	
Rise Time	t _r		Ch-1		25	50	
			Ch-2		35	70	
Turn-Off Delay Time	t _{d(off)}	Ch-1		25	50		
		Ch-2		35	70		
Fall Time	t _f	Ch-1		10	20		
		Ch-2		12	25		
Turn-On Delay Time	t _{d(on)}	Channel-1 V _{DD} = 15 V, R _L = 1.5 Ω I _D ≅ 10 A, V _{GEN} = 10 V, R _g = 1 Ω	Ch-1		10	20	
			Ch-2		12	25	
Rise Time	t _r		Ch-1		25	25	
			Ch-2		12	25	
Turn-Off Delay Time	t _{d(off)}	Ch-1		30	60		
		Ch-2		35	70		
Fall Time	t _f	Ch-1		10	20		
		Ch-2		10	20		
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	Ch-1			40	A
			Ch-2			40	
Pulse Diode Forward Current ^a	I _{SM}		Ch-1			100	
			Ch-2			120	
Body Diode Voltage	V _{SD}	I _S = 10 A, V _{GS} = 0 V	Ch-1		0.8	1.2	V
		I _S = 10 A, V _{GS} = 0 V	Ch-2		0.8	1.2	
Body Diode Reverse Recovery Time	t _{rr}	Channel-1 I _F = 10 A, dI/dt = 100 A/μs, T _J = 25 °C	Ch-1		26	50	ns
			Ch-2		36	70	
Body Diode Reverse Recovery Charge	Q _{rr}		Ch-1		25	50	nC
			Ch-2		36	70	
Reverse Recovery Fall Time	t _a	Channel-2 I _F = 10 A, dI/dt = 100 A/μs, T _J = 25 °C	Ch-1		17		ns
			Ch-2		20		
Reverse Recovery Rise Time	t _b		Ch-1		9		
			Ch-2		16		

Notes:

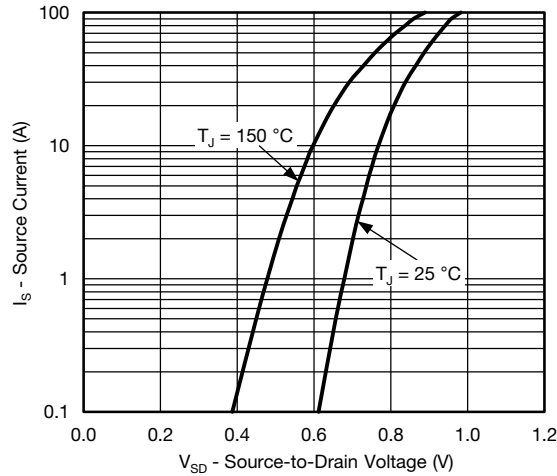
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

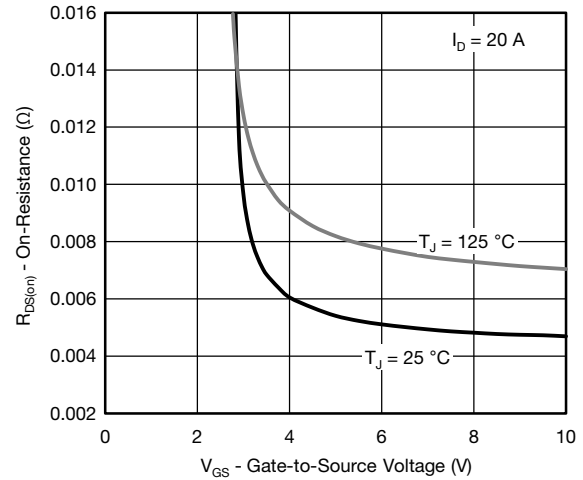
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

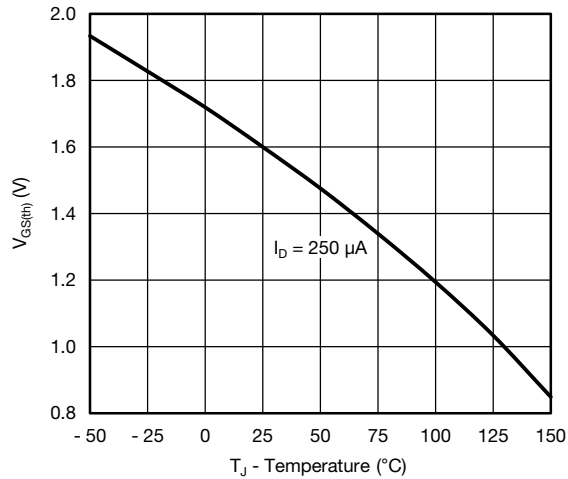
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



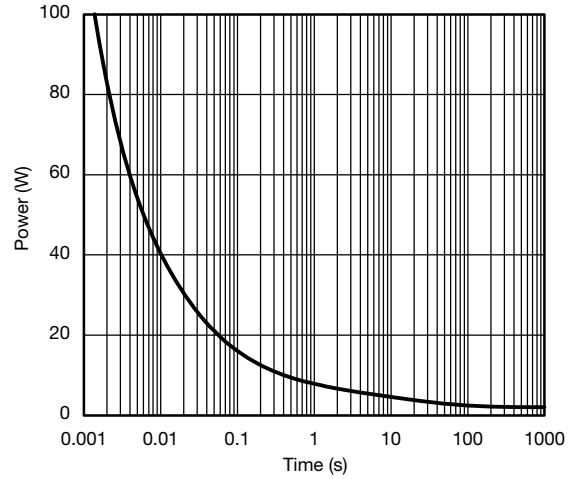
Source-Drain Diode Forward Voltage



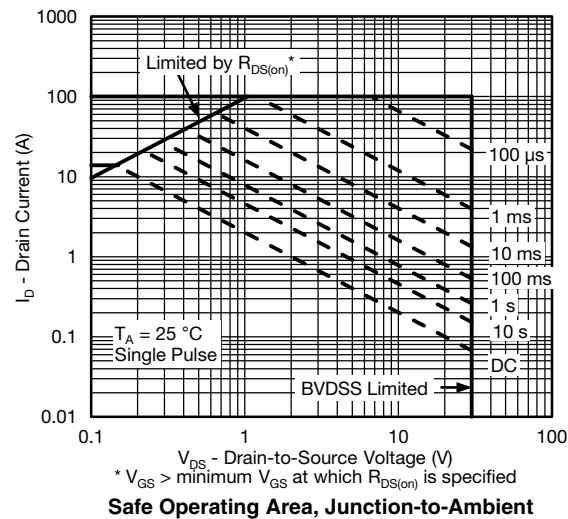
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

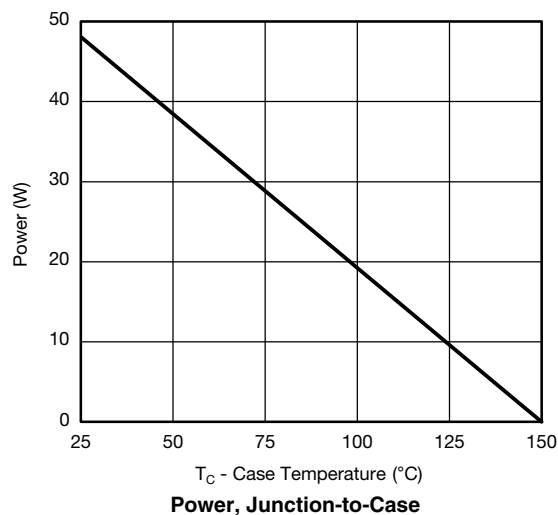
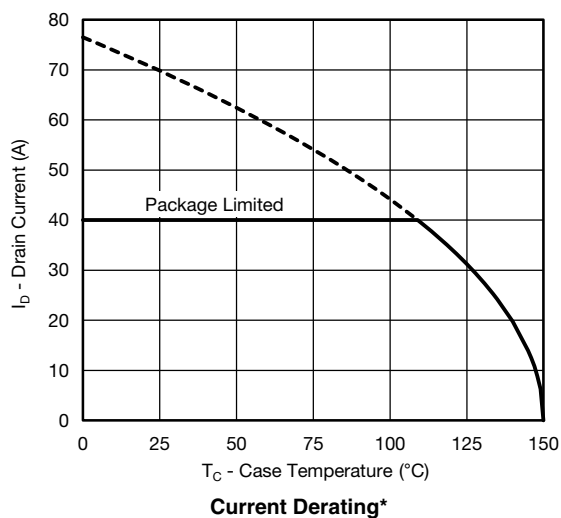


Single Pulse Power



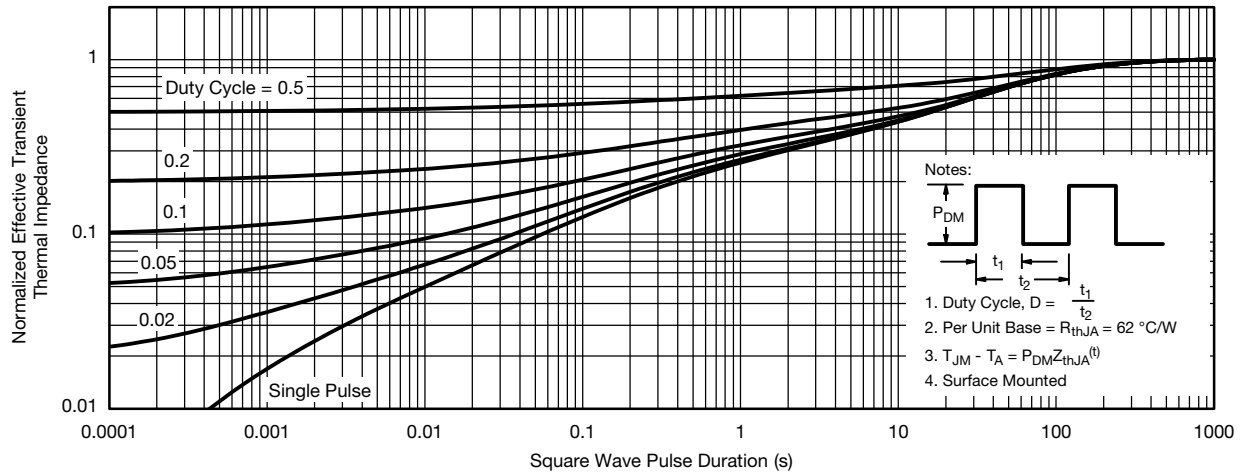
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

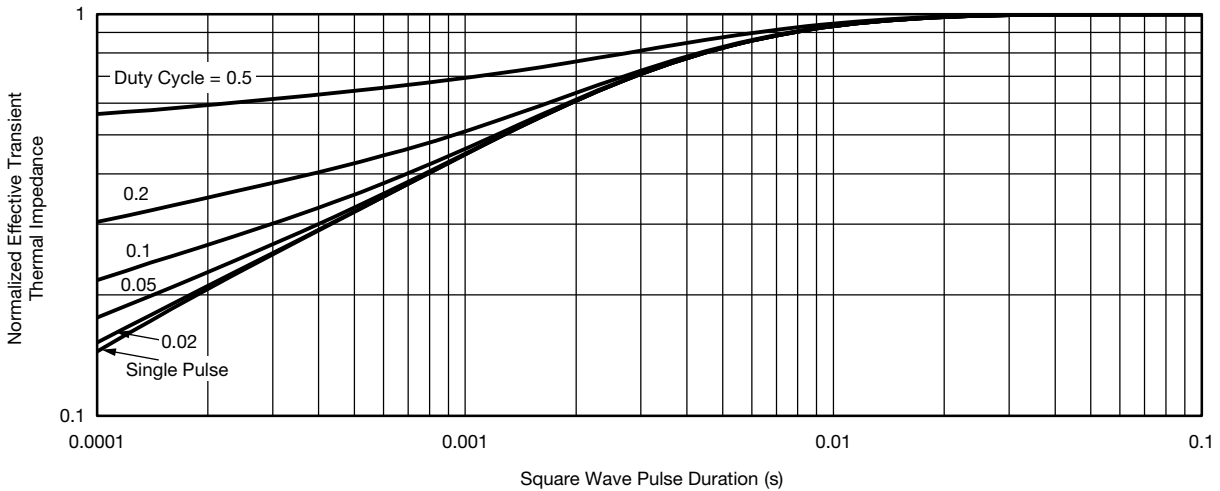
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

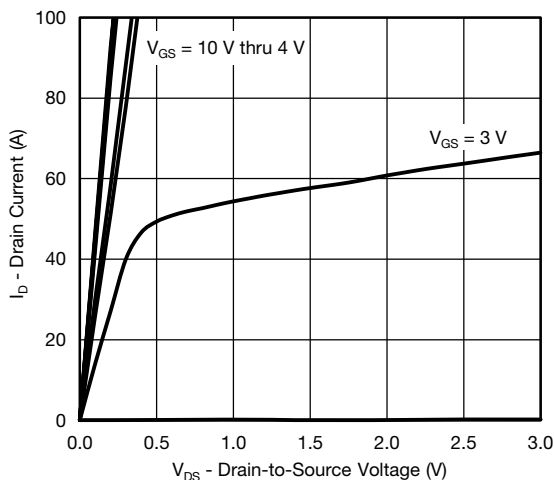
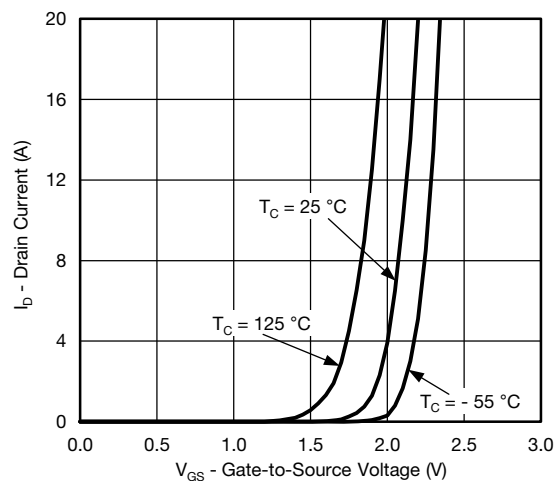
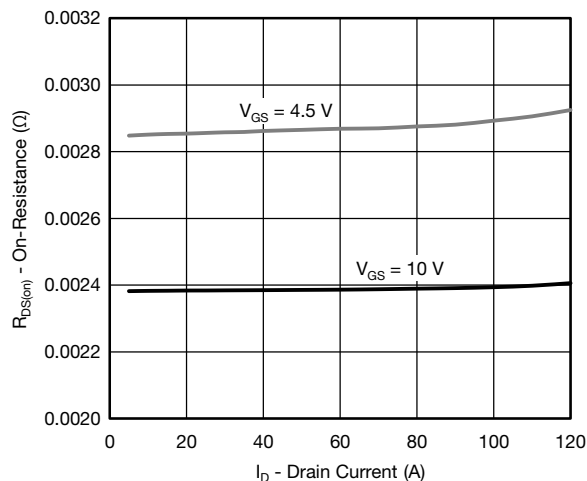
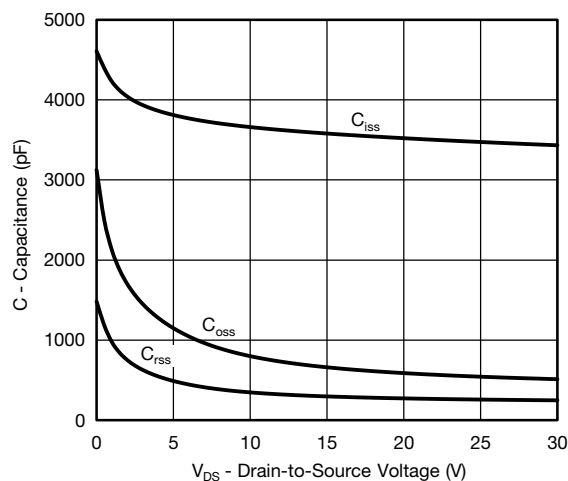
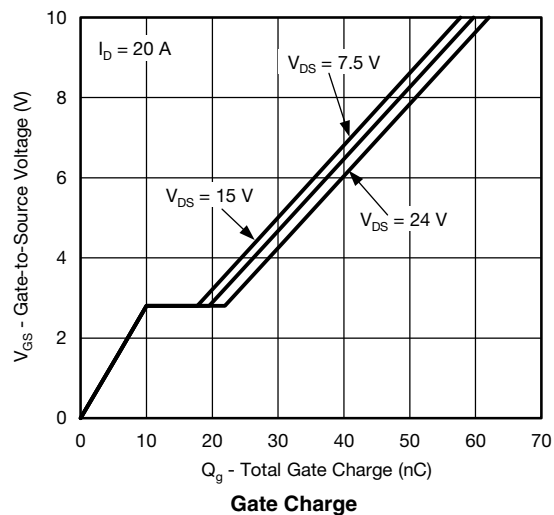
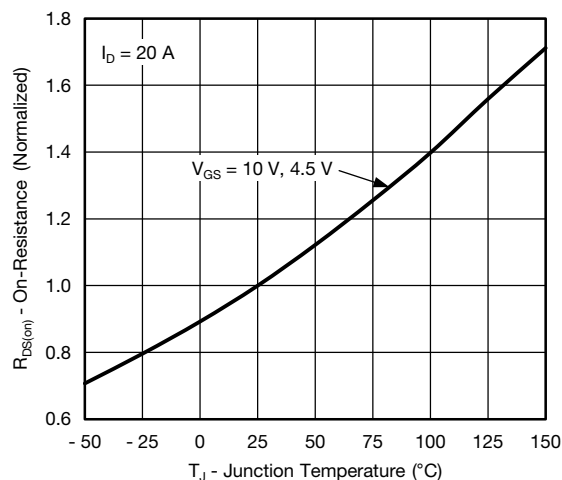
CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



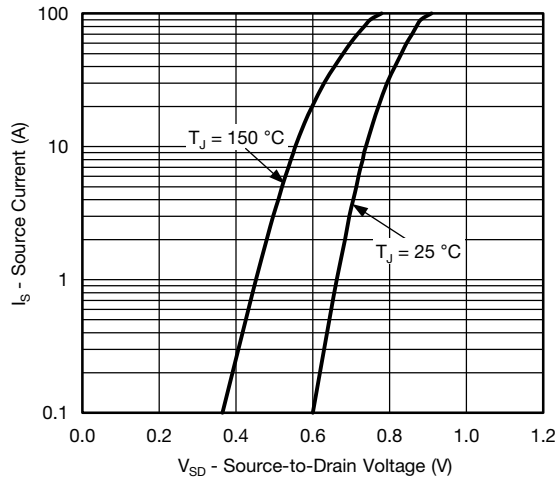
Normalized Thermal Transient Impedance, Junction-to-Ambient



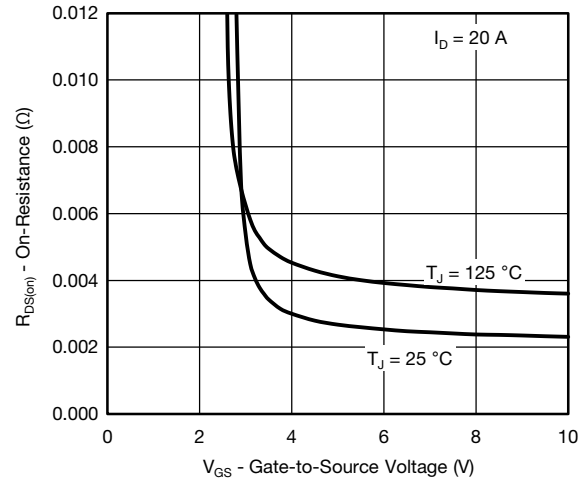
Normalized Thermal Transient Impedance, Junction-to-Case

CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)**Output Characteristics****Transfer Characteristics****On-Resistance vs. Drain Current****Capacitance****Gate Charge****On-Resistance vs. Junction Temperature**

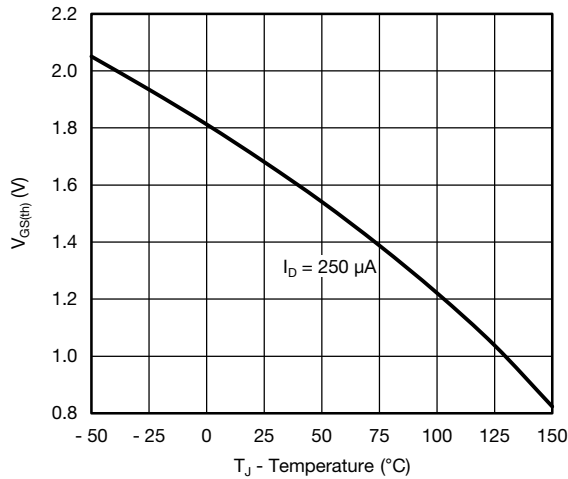
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



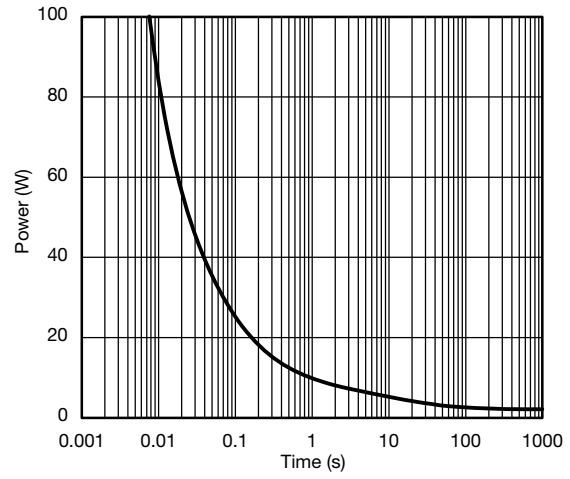
Source-Drain Diode Forward Voltage



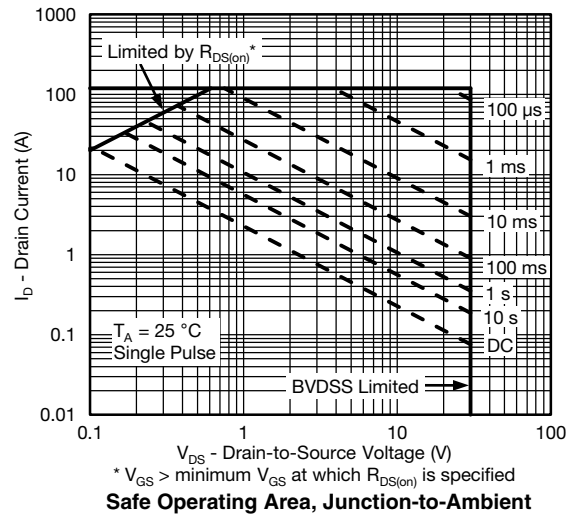
On-Resistance vs. Gate-to-Source Voltage

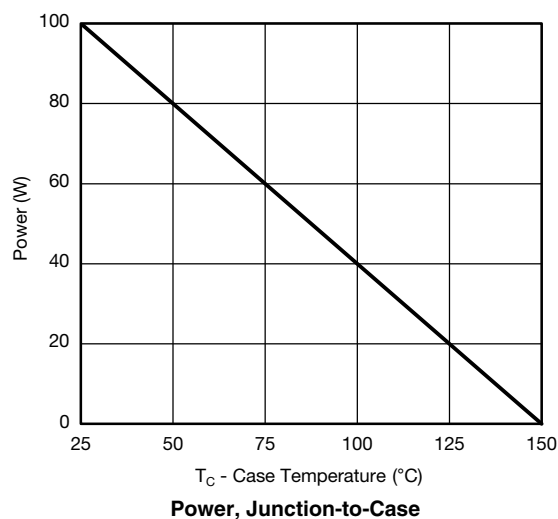
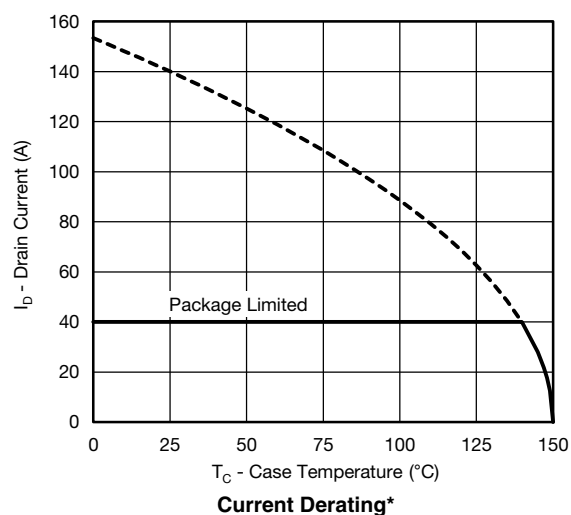


Threshold Voltage



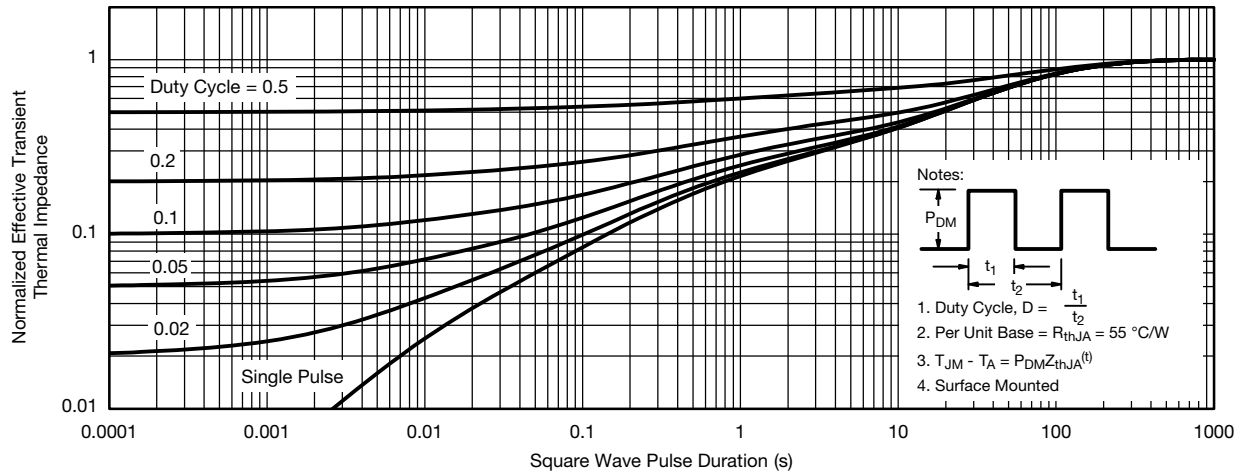
Single Pulse Power



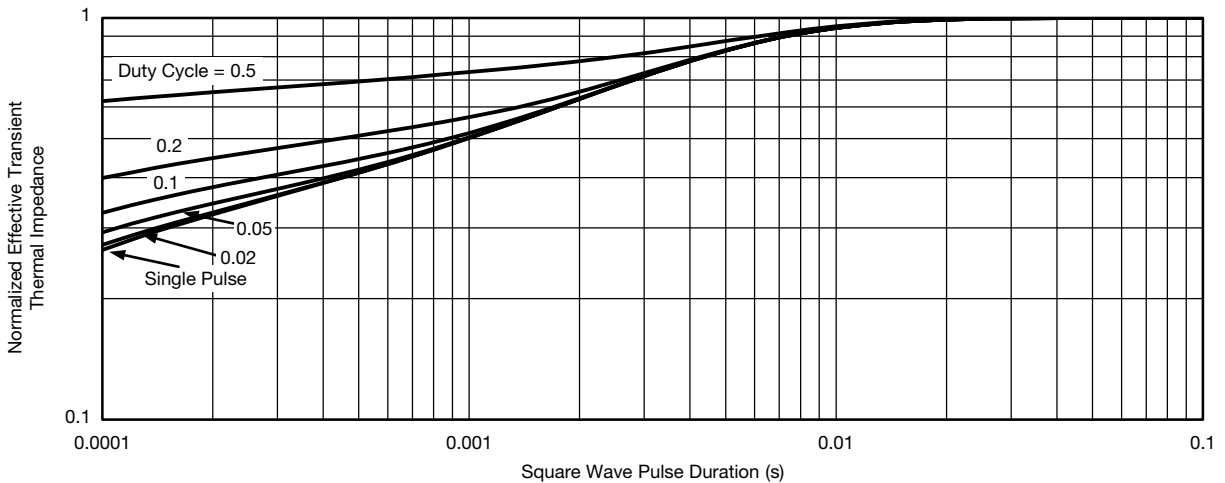
CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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